TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20260908000.1**	**PCN Issued**	September 14, 2026
Qualification of LFAB as an additional Wafer Fab site option for select devices		**Sample request deadline:**	November 13, 2026
		Estimated 1st ship date:	December 13, 2026
***Sample requests received after** November 13, 2026* **will not be supported.**			

Change type(s)
Packing/Shipping/Labeling Wafer Fab Site

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of LFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
UMC-F12	C014.M	300mm	**LFAB**	C014.M	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the Standard Data Packet for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC-F12	F12	TWN	TAINAN
LFAB	**LHI**	**USA**	**Lehi**

Sample product shipping label (not actual product label):

	

Products Affected:

AM4372BZDN80	AMIC120BZDNA30	AM4377BZDND100	AM4376BZDND80
AM4376BZDN100S	AM4372BZDNA80	AM4372BZDN60S	AM4377BZDND80
AM4376BZDN100	AM4379BZDNA100	AM4372BZDNA60S	AM4379BZDNA80S
AM4376BZDN80	AM4377BZDNA80	AM4378BZDN100	AM4376BZDND80S
AM4378BZDNA80S	AM4372BZDN60	AM4377BZDNA100	AM4372BZDNA60
AM4379BZDNA80	AM4376BZDND100	AM4372BZDN80S	AM4372BZDNA80S
AM4377BZDNA80S	AM4376BZDND30S	AM4376BZDND30	AM4378BZDNA100
AM4378BZDN100S	KUN120BZDNA30		

Approve Date 08-December - 2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Conditions					Qualification Device	Qualification by Similarity (QBS = Generic Data) Reference Devices	
Type	#	Test Name	Condition	Duration	Qual Device[1]: VF2112CZDNA60 (AM437x)	QBS Reference: AM3352BZCZ60	QBS Reference: VF2112CZDNA60
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	QBS Reference Devices	3/231/0	3/78/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	QBS Reference Devices	3/231/0	3/150/0[2]
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0 + QBS Reference Devices	3/231/0[3]	3/90/0[3]
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	QBS Reference Devices	3/135/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	QBS Reference Devices	3/230/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	QBS Reference Devices	3/2399/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	QBS Reference Devices	3/30/0	3/30/0

Conditions					Qualification Device	Qualification by Similarity (QBS = Generic Data) Reference Devices	
Type	#	Test Name	Condition	Duration	Qual Device[1]: VF2112CZDNA60 (AM437x)	QBS Reference: AM3352BZCZ60	QBS Reference: VF2112CZDNA60
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	2/60/0
BLR	-	Board Level Reliability	Board Level Reliability, Temp Cycle, 0/100C	0/100C, 7875 cyc/insitu	QBS Reference Devices	-	1/32/0

- Note 1. AM437xZDN* represents a series of products with the same technology, die, and package. The various products listed below as orderable part numbers that differ only in the features that are configured within the die. All features were enabled during the qualification stresses so the qualification results apply for all devices listed as orderable part numbers below. Additionally, AM437xZDN* is a minor extension of AM3352BZCZ60. Both use the same technology, the same fab(s) and the same package and materials; and both are qualified in UMC12A and LFAB; and both products share the same architecture, libraries, SRAM, and voltage, frequency, and temperature ranges. As a result, QBS is applicable and generic data is used for many of the stress results as noted below. Also, note that AM437xZDN* was previously qualified in UMC12A.
- Note 2. This test was completed to 1000 cycles.
- Note 3. This test was completed at an at am alternative stress condition 130C/85% RH for 192 hours. By JEDEC, this regarded as a more aggressive condition.
- QBS: Qual By Similarity, also known as Generic Data
- Qual Device AM437xZDN* and all orderable part numbers listed below are qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-082

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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